

## AMENDMENTS TO THE CLAIMS

### Listing Of Claims

Claims 1-51 (canceled)

52. (currently amended) A semiconductor component comprising:

a substrate comprising a plurality of ~~tested~~ semiconductor components, each component including a plurality of component contacts and a plurality of integrated circuits in electrical communication with the component contacts, the components including at least one defective component identified during a component testing process; and

a metal layer on the substrate comprising a plurality of separate patterns of conductors on the components in electrical communication with the component contacts configured to redistribute the component contacts on each component ~~into selected patterns~~, and to repair the defective component by connecting selected component contacts on the defective component with selected integrated circuits on the defective component, the separate patterns of conductors containing information from the component testing process for repairing the defective component.

53. (previously presented) The component of claim 52 wherein the components include a second defective component and the conductors are configured to electrically isolate the second defective component.

54. (previously presented) The component of claim 52 wherein the components include a second defective component and the conductors are configured to reconfigure the component contacts on the second defective component.

55. (previously presented) The component of claim 52 wherein the components include a second defective component and the conductors are configured to electrically connect multiple components in a cluster that excludes the second defective component.

56. (currently amended) A semiconductor component comprising:

a substrate comprising a plurality of ~~tested~~ components, each component comprising a plurality of component contacts;

~~in a plurality of patterns;~~

the components including a plurality of good components and a at least one defective component identified during a component testing process;

a metal layer on the substrate comprising a plurality of separate patterns of conductors on the components configured to redistribute ~~the patterns of~~ the component contacts ~~into selected patterns,~~ on each component and to electrically isolate the defective component on the substrate during burn-in testing of the good components, the separate patterns of conductors containing information from the component testing process for electrically isolating the defective component.

57. (currently amended) The component of claim 56 further comprising a plurality of terminal contacts on the good components ~~in the selected patterns~~ in electrical communication with the conductors and the component contacts on the good components.

58. (previously presented) The component of claim 56 wherein the conductors are configured to electrically connect a plurality of good components in a cluster that excludes the defective component.

59. (previously presented) The component of claim 56 wherein the substrate comprises a semiconductor wafer, and the components comprise semiconductor dice or semiconductor packages.

60. (currently amended) A semiconductor component comprising:

a substrate comprising a plurality of ~~tested~~ semiconductor components, each component comprising a plurality of integrated circuits and a plurality of component contacts in electrical communication with the integrated circuits, the components including at least one defective component identified during a component testing process; and

a metal layer on the substrate comprising a plurality of separate patterns of conductors on the components configured to redistribute ~~patterns of~~ the component contacts ~~into selected patterns,~~ on each component and to reconfigure the component contacts on the defective component, the separate patterns of conductors containing information from the component testing process for reconfiguring the component contacts on the defective component.

61. (currently amended) The component of claim 60 further comprising a plurality of terminal contacts on the components ~~in the selected patterns~~ in electrical communication with the conductors and the component contacts.

62. (previously presented) The component of claim 60 wherein the substrate comprises a semiconductor wafer or

portion thereof and the components comprise dice or packages.

Claims 63-69 (Canceled)

70. (currently amended) A semiconductor component comprising:

a substrate comprising a plurality of ~~tested~~ semiconductor components including a plurality of good components and at least one defective component identified during a component testing process, each component comprising a plurality of contacts and ~~in first patterns~~, a plurality of integrated circuits in electrical communication with the contacts;

a plurality of terminal contacts on the components; and  
~~in a second patterns; and~~

a metal redistribution layer on the substrate comprising a plurality of separate patterns of conductors configured to ~~redistribute the first patterns to the second patterns~~, electrically connect the contacts and the terminal contacts on each component and to electrically connect multiple components in a cluster that excludes the defective component, the separate patterns of conductors containing information from the component testing process for connecting the multiple components and excluding the defective component.

71. (currently amended) The component of claim ~~60~~ 70 wherein the terminal contacts comprise balls or bumps ~~and the second patterns comprise~~ in a plurality of separate grid arrays.

72. (currently amended) The component of claim ~~60~~ 70 wherein the contacts comprise bond pads.

73. (currently amended) The component of claim ~~60~~ 70 wherein the conductors have a fan out configuration.  
~~from the first patterns to the second patterns.~~

74. (currently amended) The component of claim ~~60~~ 70 wherein the substrate comprises a semiconductor wafer.

75. (currently amended) The component of claim ~~60~~ 70 further comprising a protective layer on the conductors having a plurality of openings for the terminal contacts.

76. (currently amended) The component of claim ~~60~~ 70 wherein the components comprise semiconductor packages or dice.

77. (currently amended) The component of claim ~~60~~ 70 wherein the components include a second defective component and the conductors are configured to repair, reconfigure or electrically isolate the second defective component.